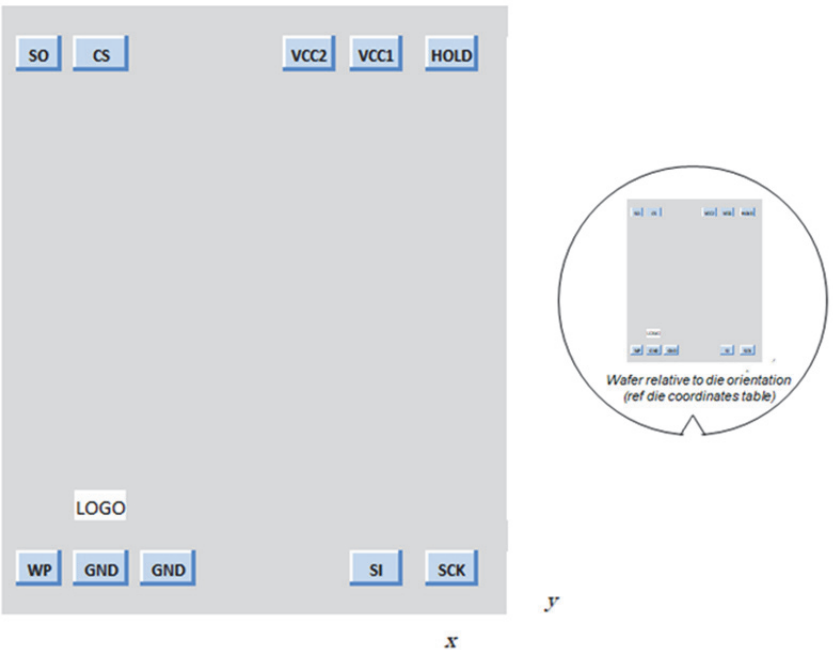


**WAFER PRODUCT DATASHEET (ADDENDUM)**

Product	AT25SF321-DWF																																															
Description	32Mbit, Standard Serial Flash, 2.5V – 3.6V VCC																																															
Die Map	 <p>Image reflects relative pad positioning only; not representative of actual die size. Reference coordinates table for actual measurements and pad position.</p>																																															
Die Size & Pad Coordinates	<table border="1"> <thead> <tr> <th></th> <th>X (μm)</th> <th>Y (μm)</th> </tr> </thead> <tbody> <tr> <td>Die Size</td> <td>2518</td> <td>1980</td> </tr> <tr> <td>Scribe Line Width</td> <td>60</td> <td>60</td> </tr> <tr> <td>Die Step</td> <td>2578</td> <td>2040</td> </tr> <tr> <td>Pad Opening</td> <td>65</td> <td>70</td> </tr> <tr> <td>CS</td> <td>225.8</td> <td>1916.1</td> </tr> <tr> <td>SO</td> <td>84.7</td> <td>1895.3</td> </tr> <tr> <td>WP</td> <td>62.2</td> <td>89</td> </tr> <tr> <td>GND</td> <td>147.2</td> <td>67.7</td> </tr> <tr> <td>GND</td> <td>232.2</td> <td>67.7</td> </tr> <tr> <td>SI</td> <td>2318.4</td> <td>64.3</td> </tr> <tr> <td>SCK</td> <td>2441.9</td> <td>90</td> </tr> <tr> <td>HOLD</td> <td>2435.5</td> <td>1897.7</td> </tr> <tr> <td>VCC1</td> <td>2336.3</td> <td>1916.7</td> </tr> <tr> <td>VCC2</td> <td>2246.3</td> <td>1895.1</td> </tr> </tbody> </table>				X (μm)	Y (μm)	Die Size	2518	1980	Scribe Line Width	60	60	Die Step	2578	2040	Pad Opening	65	70	CS	225.8	1916.1	SO	84.7	1895.3	WP	62.2	89	GND	147.2	67.7	GND	232.2	67.7	SI	2318.4	64.3	SCK	2441.9	90	HOLD	2435.5	1897.7	VCC1	2336.3	1916.7	VCC2	2246.3	1895.1
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Technical Details	
Adesto Product Family	Standard Flash
Density	32 Mbit
Operating Vcc	2.5V - 3.6V
ESD	JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	300 mm
Process Geometry (nm)	90 nm
Die ID	5405
Wafer Map	Electronic- text file
Manufacturing Facility	XMC
Wafer Thickness (µm) Maximum	800
Back Grind Options	None / Contact Adesto
Back Plane Connection	Floating / Not Required
Backside preparation / metallization	None
Bond wire qualified	AU <input checked="" type="checkbox"/> CU <input type="checkbox"/> AG <input type="checkbox"/>
Passivation Material	PETEOS + SiON
Passivation Thickness (Å)	11000
Bond Pad Material	TaN/AlCu
Bond Pad Thickness (Å)	10300
Good Die per Wafer	<a href="#">Contact Adesto</a> (AT25SF321)
Active Circuits underneath the bond pad	Yes

Part Number Ordering Code	Operating Temperature Range	Functional Specification
AT25SF321-DWF	-40°C to 85°C	<a href="http://www.adestotech.com/wp-content/uploads/DS-AT25SF321_047.pdf">http://www.adestotech.com/wp-content/uploads/DS-AT25SF321_047.pdf</a>

Revision Level – Release Date	History
A – October 2015	Initial release.
B – February 2016	Updated wafer image.
C – July 2017	Updated wafer image.

**Adesto Technologies Corporation**

3600 Peterson Way, CA 95054 | phone: (408)400-0578 fax: (408) 400-0721 | www.adestotech.com

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